



US00D827593S

(12) **United States Design Patent** (10) **Patent No.:** **US D827,593 S**
Soyano et al. (45) **Date of Patent:** **** Sep. 4, 2018**

(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/632,135**

(22) Filed: **Jan. 5, 2018**

Related U.S. Application Data

(62) Division of application No. 29/580,736, filed on Oct. 12, 2016, now Pat. No. Des. 814,433, which is a (Continued)

(30) **Foreign Application Priority Data**

Nov. 28, 2014	(JP)	D2014-026634
Nov. 28, 2014	(JP)	D2014-026635
Nov. 28, 2014	(JP)	D2014-026636

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106; D8/349, 364, 381; D23/265, 259, 262
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L

(Continued)

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor module showing our new design.

FIG. 2 is a rear view of the semiconductor module of FIG. 1.

FIG. 3 is a left side view of the semiconductor module of FIG. 1.

FIG. 4 is a right side view of the semiconductor module of FIG. 1.

FIG. 5 is a top view of the semiconductor module of FIG. 1.

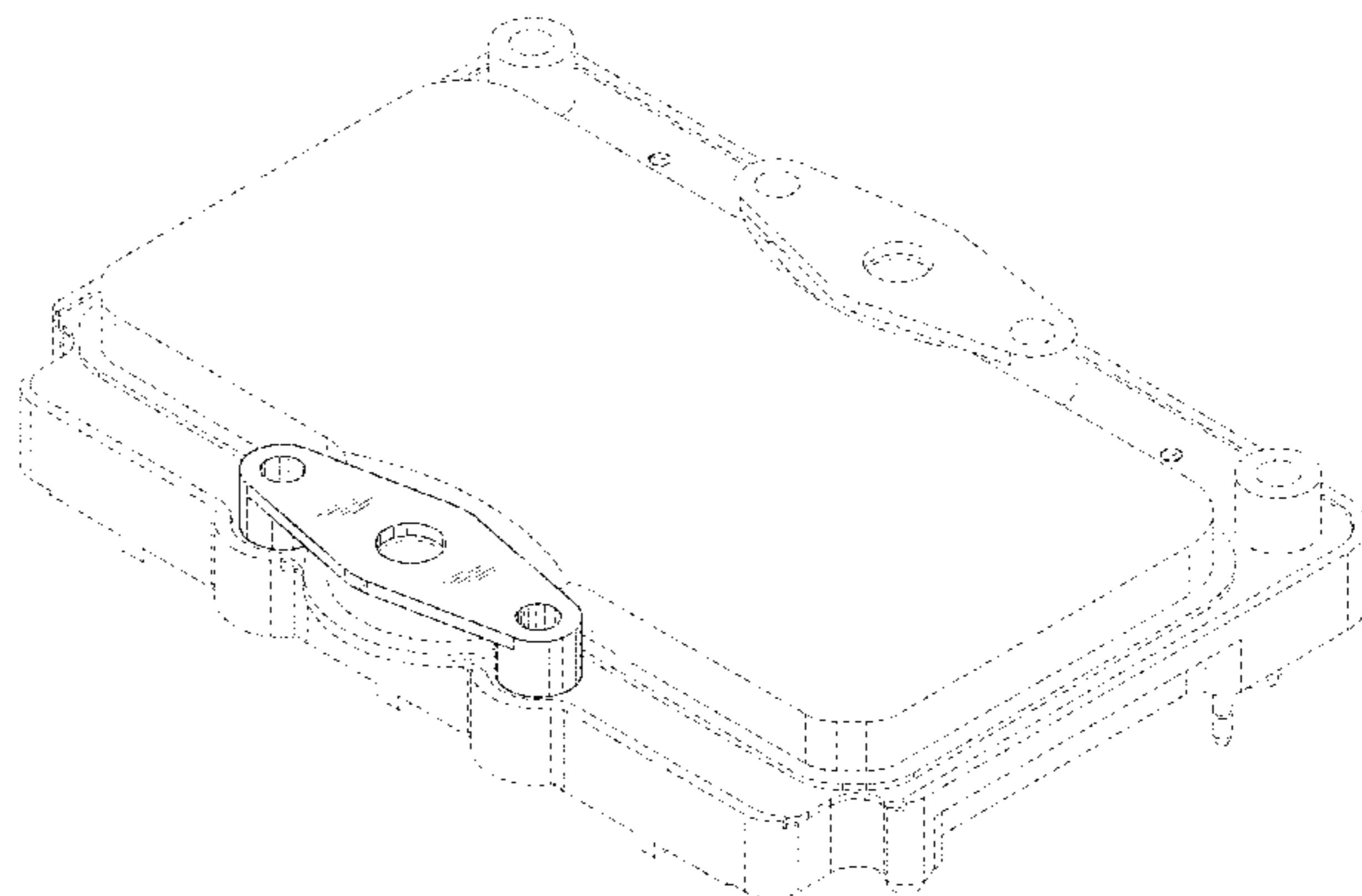
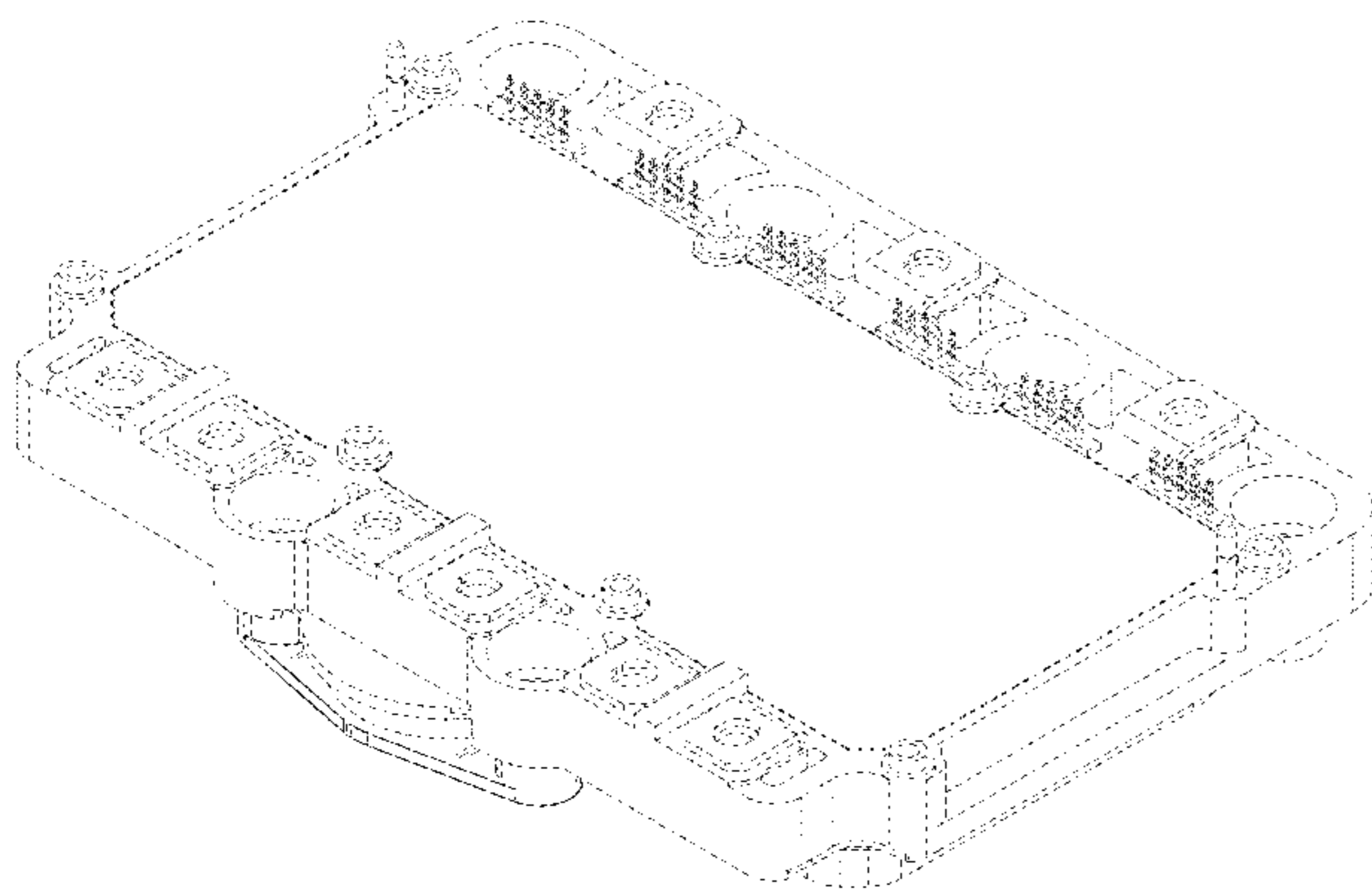
FIG. 6 is a bottom view of the semiconductor module of FIG. 1.

FIG. 7 is a front, right, and bottom perspective view of the semiconductor module of FIG. 1; and,

FIG. 8 is a rear, left, and top perspective view of the semiconductor module of FIG. 1.

The broken lines shown in the drawing views of FIGS. 1-8 form no part of the claimed design.

1 Claim, 8 Drawing Sheets



Related U.S. Application Data

division of application No. 29/528,214, filed on May 27, 2015, now Pat. No. Des. 774,479.

(58) **Field of Classification Search**

CPC 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/428; G02B 6/4281; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026

See application file for complete search history.

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FIG. 1

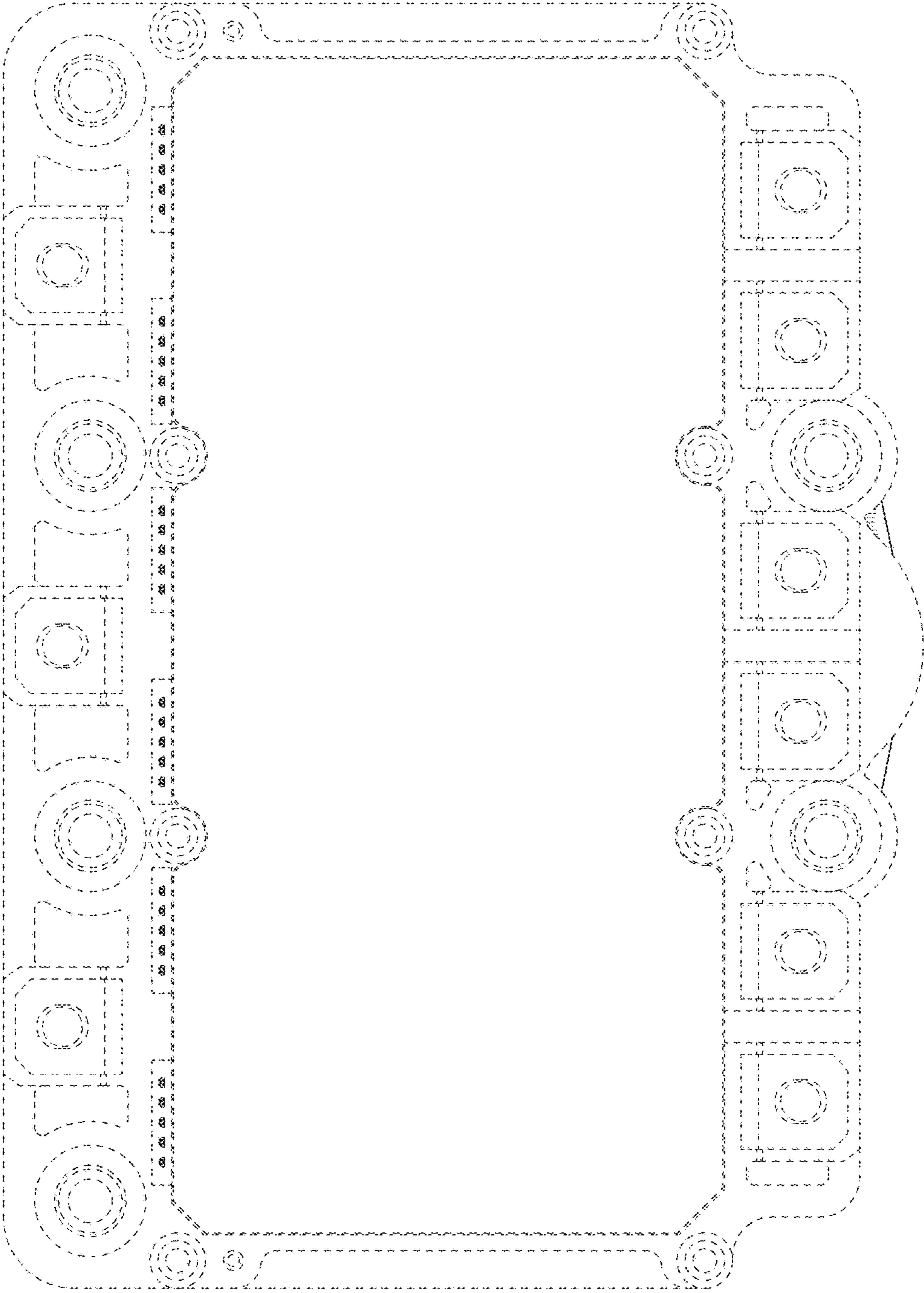


FIG. 2

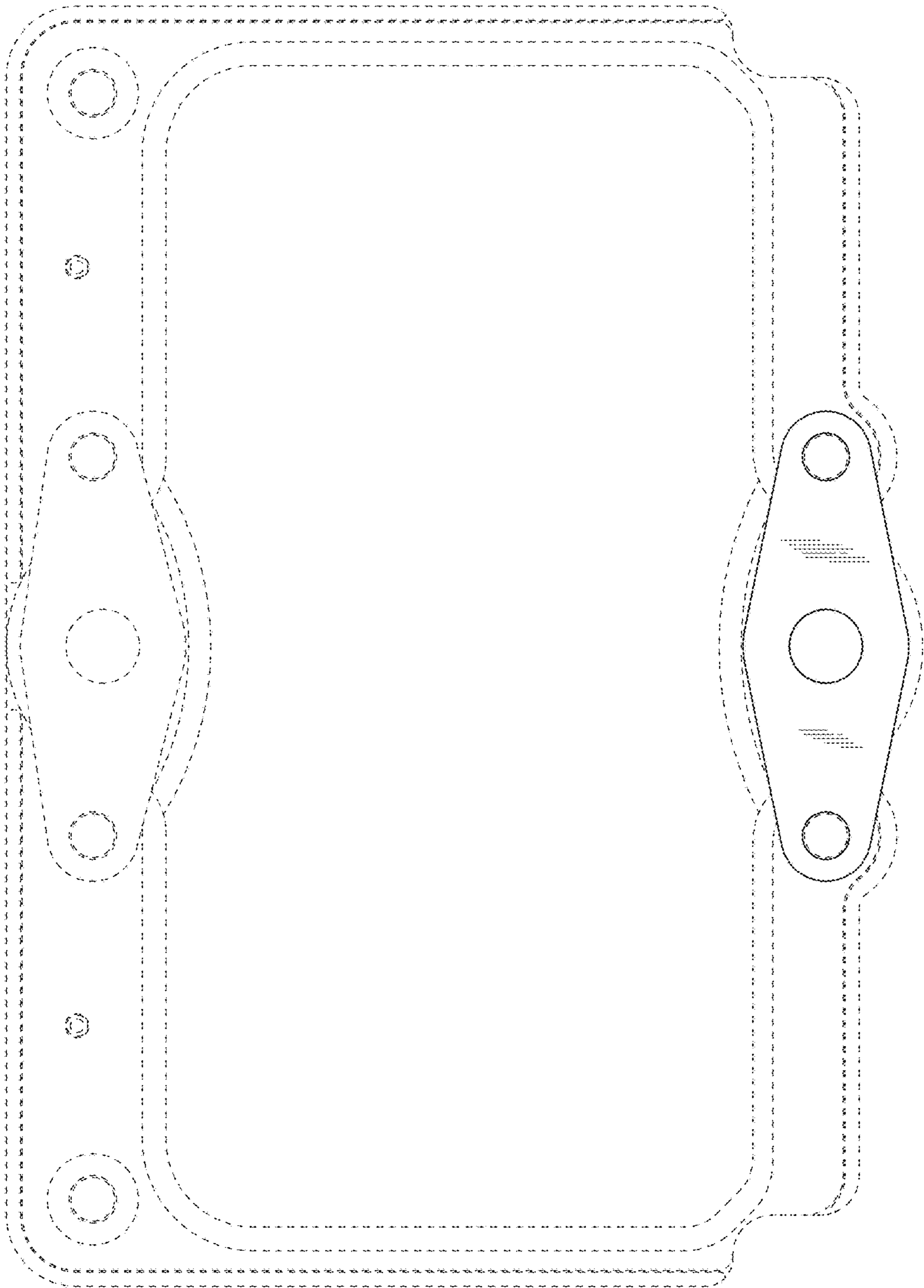


FIG. 3

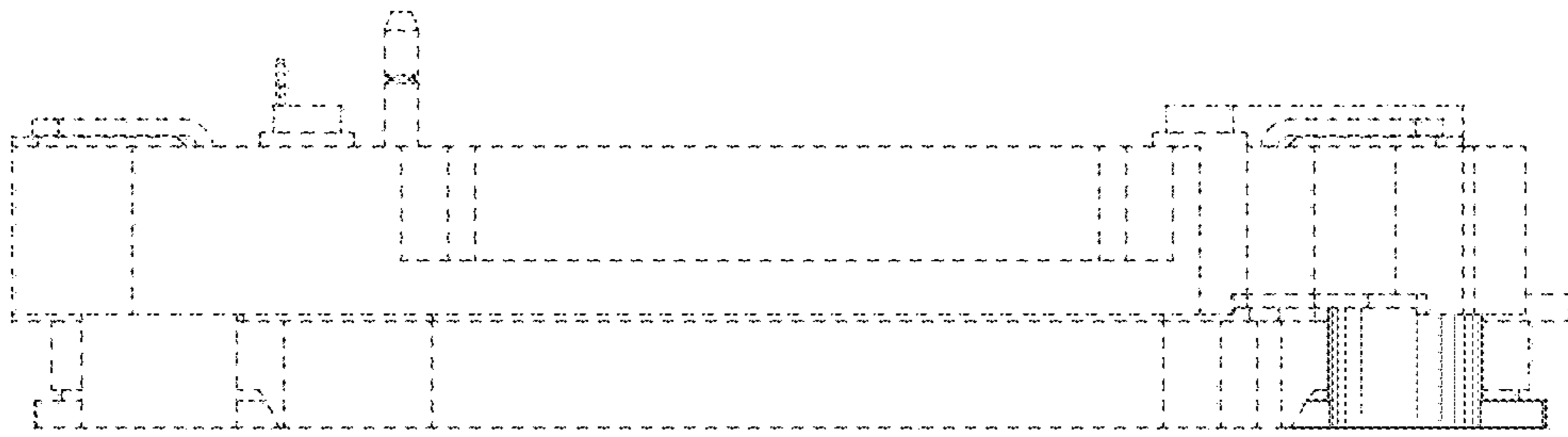


FIG. 4

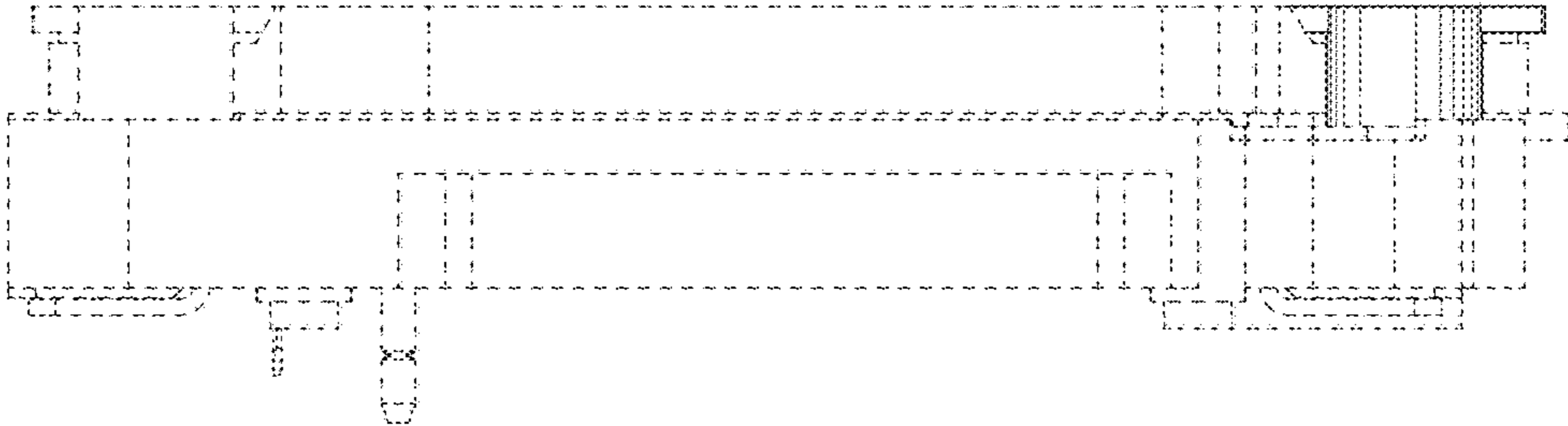


FIG. 5

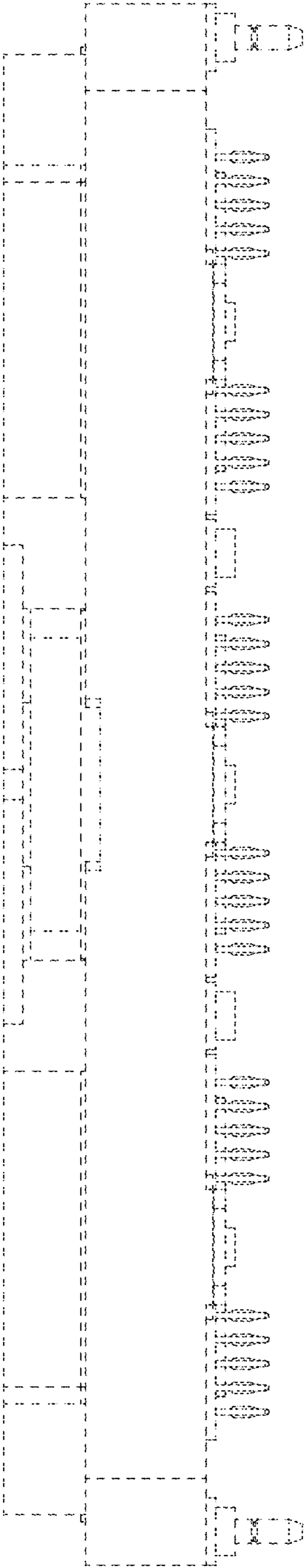


FIG. 6

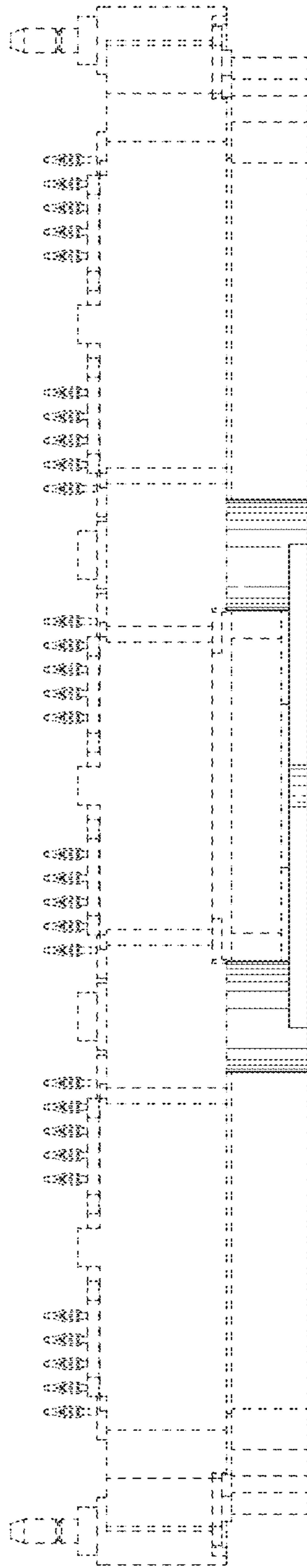


FIG. 7

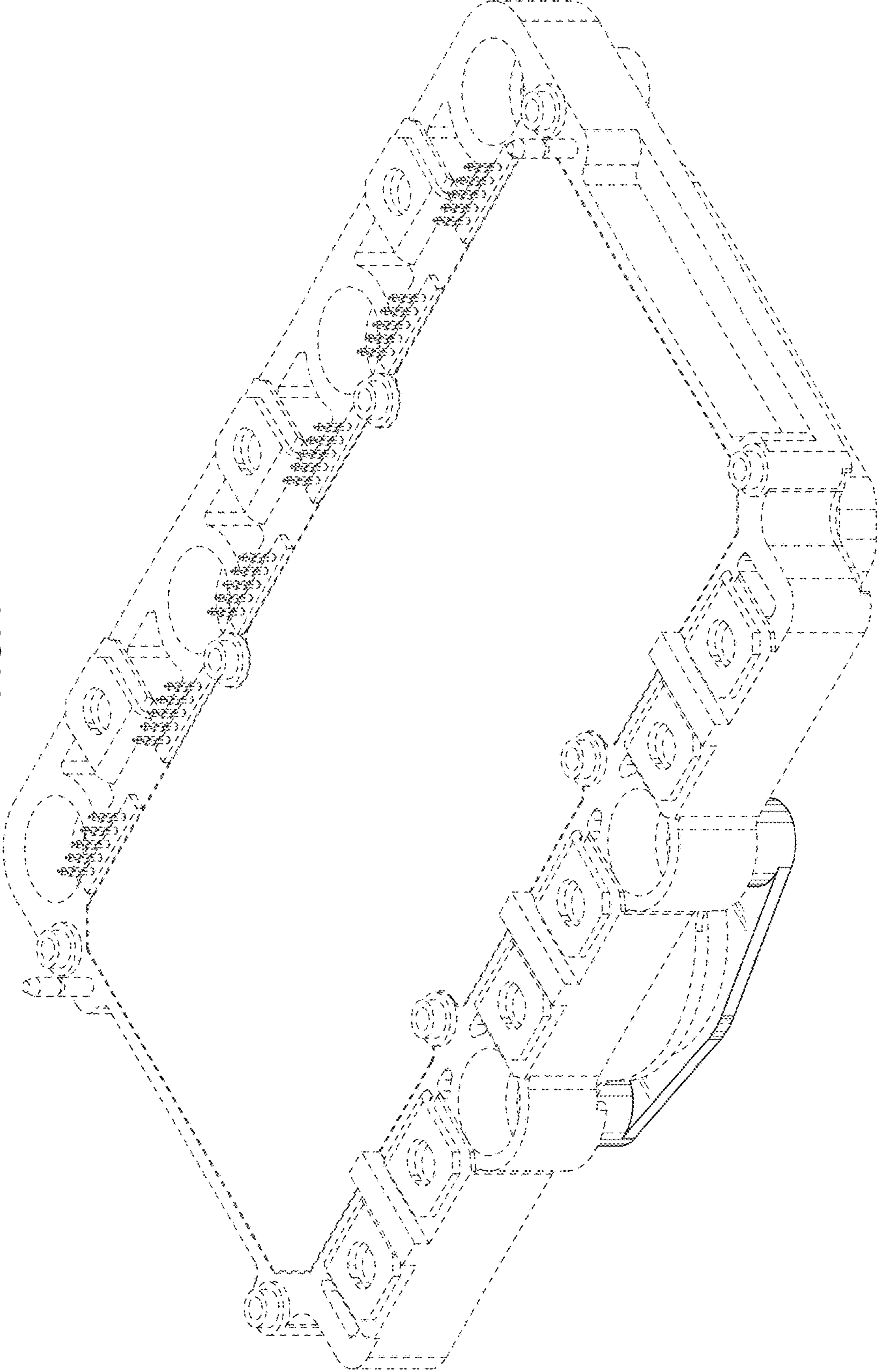


FIG. 8

